

Final Product Change Notification

202110009F01: Transition from xJA1124yHG/0 to Drop-in Replacement xJA1124yHG/1

Note: This notice is NXP Company Proprietary.

Issue Date: Dec 31, 2022 Effective date:Mar 31, 2023

Dear Collette Sannes-Neste,

Here is your personalized notification about a NXP general announcement. For detailed information we invite you to view this notification online

Management summary

The types SJA1124xHG/0 and TJA1124xHG/0 will be replaced by the types SJA1124xHG/1 and TJA1124xHG/1. A minor update was done in the digital part of the dies, to correct a start-up issue a customer reported.

Change Category

[]Water Fab Process	[]Assembly Process	[X]Product Marking	[]Test Process	[X]Design		
[]Wafer Fab Materials	[]Assembly Materials	[]Mechanical Specification	[]Test Equipment	[]Errata		
[]Wafer Fab Location	[]Assembly Location	[]Packing/Shipping/Labeling	[]Test Location	[]Electrical spec./Test coverage		
[]Eirmwara	[V]Other: A new datasheet will be issued					

[]Firmware [X]Other: A new datasheet will be issued.

PCN Overview

Description

The types SJA1124xHG/0 and TJA1124xHG/0 will be replaced by the types SJA1124xHG/1 and TJA1124xHG/1. A minor update was done in the digital part of the dies.

Details of the change are in the attachment to this PCN. The change also resulted in a minor update of the datasheet, which is also explained in the attachment to this PCN.

The old products will be discontinued per DN (Discontinuation Notice). The DN will be published in due time, there will be an opportunity for an all-time-buy, as described in the NXP DN procedure.

Reason

Under very specific conditions, a customer found a start-up issue, which needed to be corrected.

Identification of Affected Products

Top Side Marking

See the attached file.

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipmentDec 12, 2022

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

A new datasheet will be issued

Disposition of Old Products

The old version of the types will remain available.

Additional information

Self qualification: view online
Additional documents: view online

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Jan 30, 2023.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Henry van Mook

Position Quality Account Manageer

e-mail

address <u>ivn.customer.service@nxp.com</u>

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.

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